

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT7007231

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT

**CONVEYING PARTY DATA**

Name	Execution Date
CHIA-HAN LIN	02/21/2018
CHIEN-FA LEE	02/21/2018
HSU-SHUI LIU	02/21/2018
JIUN-RONG PAI	02/21/2018
SHENG-HSIANG CHUANG	02/21/2018
SURENDRA KUMAR SONI	02/21/2018
SHOU-WEN KUO	02/21/2018
WU-AN WENG	02/22/2018
GARY TSAI	02/22/2018
CHIEN-KO LIAO	02/21/2018
YA HSUN HSUEH	02/21/2018
BECKY LIAO	02/21/2018
ETHAN YU	02/21/2018
MING-CHI TSAI	02/22/2018
KUO-YI LIU	02/22/2018

**RECEIVING PARTY DATA**

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<b>City:</b>	HSINCHU
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	300-78

**PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	17518918

**CORRESPONDENCE DATA**

**Fax Number:** (216)502-0601

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**PATENT**

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<b>ATTORNEY DOCKET NUMBER:</b>	TSMCP843USB
<b>NAME OF SUBMITTER:</b>	DAVID W. POTASHNIK
<b>SIGNATURE:</b>	/David W. Potashnik/
<b>DATE SIGNED:</b>	11/04/2021

**Total Attachments: 17**

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PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT

Assignor(s):  
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Assignor(s):  
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Assignor(s):  
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Surendra Kumar Soni

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Assignor(s):  
Wu-An Weng

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Gary Tsai

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Assignor(s):  
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TSMC Docket No. P20171745US00  
Docket No. TSMCP843US

Assignee:

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Republic of China

**AGREEMENT**

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled

**"AUTOMATED INSPECTION TOOL"** for which:

a non-provisional application for United States Letters Patent:

☒ was executed on even date preparatory to filing (each inventor should sign this Assignment on the same day as he/she signs the Declaration); or

☐ was filed on \_\_\_\_\_ and accorded U.S. Serial No. \_\_\_\_\_; or

☐ I hereby authorize and request my attorney associated with Customer No. 107476, to insert on the designated lines below the filing date and application number of said application when known:

U.S. Serial No. \_\_\_\_\_,

filed on \_\_\_\_\_.

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and

in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

2018/02/21  
Date

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TSMC Docket No. P20171745US00

Docket No. TSMCP843US

3/1/2018  
Date

Chin-Ya Lee  
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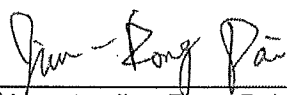
TSMC Docket No. P20171745US00  
Docket No. TSMCP843US

2018.2.21  
Date

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TSMC Docket No. P20171745US00  
Docket No. TSMCP843US

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Date

  
Name 4<sup>th</sup> Inventor Jiun-Rong Pai



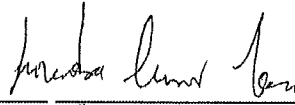
TSMC Docket No. P20171745US00  
Docket No. TSMCP843US

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TSMC Docket No. P20171745US00  
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TSMC Docket No. P20171745US00  
Docket No. TSMCP843US

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TSMC Docket No. P20171745US00  
Docket No. TSMCP843US

2018/2/22  
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Docket No. TSMCP843US

2018/2/22  
Date

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Docket No. TSMCP843US

2018/02/21  
Date

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Docket No. TSMCP843US

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Docket No. TSMCP843US

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Date

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TSMC Docket No. P20171745US00  
Docket No. TSMCP843US

2018/02/21  
Date

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TSMC Docket No. P20171745US00  
Docket No. TSMCP843US

2018/2/22  
Date

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TSMC Docket No. P20171745US00  
Docket No. TSMCP843US

2018/2/22  
Date

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